Electronic Filing System (EFS) Data **Electronic Patent Application Submission USPTO** Use Only

EFS ID:

60527

Application ID:

10626150

Title of Invention:

PLASTIC INTEGRATED CIRCUIT PACKAGE AND METHOD AND

LEADFRAME FOR MAKING THE

PACKAGE

First Named Inventor:

THOMAS GLENN

Domestic/Foreign Application: Domestic Application

Filing Date:

2003-07-24

Effective Receipt Date:

2004-05-06

Submission Type:

Information Disclosure

Filing Type:

Confirmation number:

9302

Attorney Docket Number:

AMKOR007C2

Total Fees Authorized:

Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark

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Electronic Version v1.1
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Title of Invention

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Application Number:

10/626150

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First Named Applicant:

THOMAS P.

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Documents being submitted

Files

us-ids

ids3-usidst.xml

us-ids.dtd

us-ids.xsl

Comments



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18 Stylesheet Version v18.0

> Title of Invention

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Attorney Docket Number: AMKOR007C2

Art Unit:

2815

Search string:

(5608265 or 5608267 or 5625222 or 5633528 or 5639990 or 5640047 or 5641997 or 5643433 or 5644169 or 5646831 or 5650663 or 5661088 or 5665996 or 5673479 or 5683806 or 5689135 or 5696666 or 5701034 or 5703407 or 5710064 or 5724233 or 5723899 or 5726493 or 5736432 or 5745984 or 5753532 or 5753977 or 5766972 or 5770888 or 5776798 or 5783861 or 5801440 or 5814877 or 5814881 or 5814883 or 5814884 or 5817540 or 5818105 or 5821457 or 5821615 or 5834830 or 5835988 or 5844306 or 5856911 or 5859471 or 5866939 or 5871782 or 5874784 or

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

5877043 or 5886397).pn.

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	5608265	1997-03-04	Kitano et al.			
	2	5608267	1997-03-04	Mahulikar et al.			
	3	5625222	1997-04-29	Yoneda et al.			
	4	5633528	1997-05-27	Abbott et al.			
	5	5639990	1997-06-17	Nishihara et al.			
	6	5640047	1997-06-17	Nakashima			
	7	5641997	1997-06-24	Ohta et al.			
	8	5643433	1997-07-01	Fukase et al.			
	9	5644169	1997-07-01	Chun			
	10	5646831	1997-07-08	Manteghi			İ

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7.4.				
	11	5650663	1997-07-22	Parthasaranthi
	12	5661088	1997-08-26	Tessier et al.
	13	5665996.	1997-09-09	Williams et al.
	14	5673479	1997-10-07	Hawthorne
	15	5683806	1997-11-04	Sakumoto et al.
	16	5689135	1997-11-18	Ball
	17	5696666	1997-12-09	Miles et al.
	18	5701034	1997-12-23	Marrs
	19	5703407	1997-12-30	Hori
	20	5710064	1998-01-20	Song et al.
	21	5724233	1998-03-03	Honda et al.
	22	5723899	1998-03-03	Shin
	23	5726493	1998-03-10	Yamashita
	24	5736432	1998-04-07	Mackessy
	25	5745984	1998-05-05	Cole, Jr. et al.
	26	5753532	1998-05-19	Sim
	27	5753977	1998-05-19	Kusaka et al.
	28	5766972	1998-06-16	Takahashi et al.
	29	5770888	1998-06-23	Song et al.
	30	5776798	1998-07-07	Quan et al.
	31	5783861	1998-07-21	Son
	32	5801440	1998-09-01	Chu et al.
	33	5814877	1998-09-29	Diffenderfer et al.
	34	5814881	1998-09-29	Alagaratnam et al.
	35	5814883	1998-09-29	Sawai et al.
	36	5814884	1998-09-29	Davis et al.
	37	5817540	1998-10-06	Wark
	38	5818105	1998-10-06	Kouda
	39	5821457	1998-10-13	Mosley et al.
	40	5821615	1998-10-13	Lee
	.41	5834830	1998-11-10	Cho
	42	5835988	1998-11-10	Ishii
	43	5844306	1998-12-01	Fujita et al.
	44	5856911	1999-01-05	Riley
	45	5859471	1999-01-12	Kuraishi et al.
	46	5866939	1999-02-02	Shin et al.



N. OFF.	47	5871782	1999-02-16	Choi
	48	5874784	1999-02-23	Aoki, et al.
	49	5877043	1999-03-02	Alcoe et al.
	50	5886397	1999-03-23	Ewer

Signature

Examiner Name	Date	